JPCA 2026 Show
55th International Electronic Circuits Exhibition
Organizer: JPCA-Japan Electronics Packaging and Circuits Association

JIEP 2026 Microelectronics Show
40th ADVANCED ELECTRONICS PACKAGING EXHIBITION
Organizer: JIEP Japan Institute of Electronics Packaging

JISSO PROTEC 2026
27th Jisso Process Technology Exhibition
Organizer: Japan Robot Association (JARA)

AI Device Expo
Co-Organizer: JPCA-Japan Electronics Packaging and Circuits Association, Electronic Device Industry News (Sangyo Times Inc.)

Connecting Machine to Machine
WIRE Japan Show 2026
Electrical /Optical Transmission Technology
Co-Organizer: JPCA-Japan Electronics Packaging and Circuits Association
THE ELECTRIC WIRE & CABLE NEWS (KOGYO TSUSHIN CO., LTD.)

Electronics Component & Unit Show
JEP Japan Federation of Electronic Parts Distributors and Dealers
Tokyo Electronics Appliances Wholesalers Association

E-Textile/Wearable
Organizer: JPCA-Japan Electronics Packaging and Circuits Association

Semiconductor Technology Expo Japan
Co-Organizer: JPCA -Japan Electronics Packaging and Circuits Association
Innovent, Inc.

OSAT SOLUTION SHOW
Co-Organizer: JPCA -Japan Electronics Packaging and Circuits Association
Japan OSAT Association

The Exhibition Guide

2026.6.10 Wed. → 12 Fri. **Tokyo Big Sight, East Exhibition Halls**

The Total Solution Exhibition for Electronic Equipment 2026

Application to Exhibit from: 10:00 am (JST), November 14, 2025

Official Website

Organizers: Japan Electronics Packaging and Circuits Association, Japan Institute of Electronics Packaging, Japan Robot Association
Co-organizers: Electronic Device Industry News (Sangyo Times, Inc.)
Electric Wire & Cable News (KOGYO TSUSHIN CO., LTD)
Japan Federation Of Electronic Parts Distributors and Dealers
Tokyo Electronics Appliances Wholesalers Association
Innovent, Inc.
Japan OSAT Federation
Sponsor (tentative): Ministry of Economy, Trade and Industry

Overseas Cooperation:
World Electronic Circuits Council (WECC) Member Associates:
China Printed Circuit Association (CPCA), European Institute of Printed Circuits (EIPC), Hong Kong Printed Circuit Association (HKPCA), Global Electronics Association (IPC), Indian Printed Circuit Association (IPCA), Electronic Industries Association of India (ELCINA), Korea Printed Circuit Association (KPCA), Thailand Printed Circuit Association (THPCA), Taiwan Printed Circuit Association (TPCA)

Korea Packaging Integration Association (KPIA)

As of Nov.11, 2025

Everything that brings electronics to life is here!

The theme for the 2026 exhibition is "Technology no Tenkomori! From Semiconductors to Electronic Devices." With the addition of the new Semiconductor Technology Expo Japan and OSAT Solution Show, more than 400 exhibitors(planned) specializing in electronic circuit boards, assembly, equipment, processes, and electronic components will gather to present the very best in technology. This event offers an exceptional opportunity to experience the world's most advanced innovations.

Exhibition Outline

Exhibition Period Wednesday, June 10 to Friday, June 12, 2026, 10:00 a.m. - 5:00 p.m. JST

Venue Tokyo Big Sight East Exhibition Halls

Managed by Japan Electronics Packaging and Circuits Association (JPCA)

Admission 1,000 Yen (including tax)

* Free Admission for those who have pre-registered online.

Secretariat Office SHOEI Bijutsu CO.,LTD

Attractive Seminar Programs/Events

PCB, Assembly, PCB Related Equipment, Materials/Processes, High-speed Transmission Technology for Autonomous Driving, High-current Technology for EVs, Advanced Packaging Technology, Materials and Process Technology for Power Semiconductors/Glass Substrates, Low-emission Technology for Climate Change, E-Textile/Wearable Technology, Sensor & Sensing Technology, Automated Technology/ Solutions, Edge Computing, On-Device technology, etc.

Exhibitions held inside the exhibition/relevant exhibits

Electronic circuits technology

JPCA 2026 Show
55th International Electronic Circuits Exhibition
Organizer: JPCA-Japan Electronics Packaging and Circuits Association

- **PWB Tech**
  Products and Technologies related to electronic circuit boards (Design & Simulation, Reliability& Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment,Related Systems), etc.
- **Module JAPAN**
  Module board / Module Board mounting / Embedded Component Board, General technology for built-in parts (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems) ,etc.
- **Flexible Printed Circuits Products Area**
  General technology for Flexible Printed Circuits (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems)
- **EMS Japan**
  Services and technologies related to EMS, ODM and contract manufacturing of semiconductors(Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems)

Organizer: Japan Electronics Packaging and Circuits Association

High-density packaging technologies

JIEP 2026 Microelectronics Show
40th ADVANCED ELECTRONICS PACKAGING EXHIBITION
Organizer: JIEP Japan Institute of Electronics Packaging

General technology for implementation and electric technology (Materials / Circuit and Mounting design / High speed high frequency / Electromagnetic properties / Electronic parts / mounting / Optical circuit mounting / Environmental affinity implementation / Semiconductor Package / Micro mechatronics mounting technology / Related Manufacturing equipment)

Organizer:
Japan Institute of Electronics Packaging

Electronic Component Packaging Technologies

JISSO PROTEC 2026
27th Jisso Process Technology Exhibition
Organizer: Japan Robot Association (JARA)

- ■ Electronic Component Placement Machines and related Equipment and Systems: electronic component placement machines (Mounter), electronic component insertion machines (Inserter), screen printers, soldering equipment (reflow oven), and dispensers
- ■ Packaging related Equipment and Systems:
  transfer systems, AGV, automatic warehouse, taping machines and materials, bulk feeders and other feeders, and automatic assembly machines, laser marking machine, cleaning equipment · cleaner
- ■ Semiconductor Packaging Machines and Systems:
  bonding equipment, flip chip packaging systems,COB systems
- ■ Industrial Robotics: handling robots, assembly robots, transport robots
- ■ Inspection/Test Equipment:
  automated optical inspection equipment, inspection/measuring equipment associated with semiconductor manufacturing
- ■ Packaging Design Systems: design tools, production optimizing software, and packaging programming equipment
- ■Packaging Device Packaging Materials
- ■Packaging Joining Systems · Solder/joining materials
- ■High Frequency Compatible Devices, Components, and Materials
- ■Environment related Devices and Materials

Organizer: Japan Robot Association

AI Device

AI Device Expo

Smart devices, Smart home devices,Wearable devices, AI devices for robotics, AI devices for industrial robotics, Smart devices, Smart home devices, Wearable devices, AI devices for industrial robotics devices, AI devices for industrial robotics, Self-driving technology, AI software and platforms forms, Virtual assistants, Educational AI, Medical AI, Security AI, Data analysis tools, etc.

Co-organizers: Japan Electronics Packaging and Circuits Association, Electronic Device Industry News (Sangyo Times, Inc.)

Electrical/optical transmission technology

Connecting Machine to Machine
WIRE Japan Show
Electrical /Optical Transmission Technology

General transmission technology for using wire and cable (Industrial equipment / Electrical wire, cable and connector / Electric wire processing machine / Wiring material / Wire Harness / Measuring instrument for electric wire and cable / Various devices + D116 / Inspection technology / M2M transmission / Optical transmission)

Co-organizers: Japan Electronics Packaging and Circuits Association, Cable News (KOGYO TSUSHIN CO., LTD)

Semiconductors and Electronic parts

Electronics Component & Unit Show
JEP Japan Federation of Electronic Parts Distributors and Dealers
Tokyo Electronics Appliances Wholesalers Association

General technology for solutions by Semiconductors and Electronic parts (Semiconductors / Electronic Devices / Sensors / Mechanical Devices / FA control equipments / Measuring instruments / Power Sources / IoT and M2M Solution / Manufacturing solution system)

Co-organizers: Japan Federation Of Electronic Parts Distributors And Dealers, Tokyo Electronics Appliances Wholesalers Association

Highly functional textile

E-Textile/Wearable

A mix e-textile of electronic technology, fiber and clothing (General technology for smart textile, stretchable and wearable (Textile material / Conductive material / material / Knitting / weaving technology / Print marking technology / Films)

Co-organizers: Japan Electronics Packaging and Circuits Association

NEW Semiconductors

Semiconductor Technology Expo Japan

Semiconductor design services / tools / contract design, semiconductor manufacturing equipment / facilities / software, semiconductor manufacturing components / materials, semiconductor inspection / testing / measurement / analysis equipment and services, factory equipment / supplies for semiconductor plants, staffing / logistics services for the semiconductor industry, and other semiconductor-related products / services.

*For those wishing to exhibit at the Semiconductor Technology Expo Japan, please inquire via the Semiconductor Technology Expo Japan website.

Co-organizers:
Japan Electronics Packaging and Circuits Association (JPCA), Innovent, Inc.

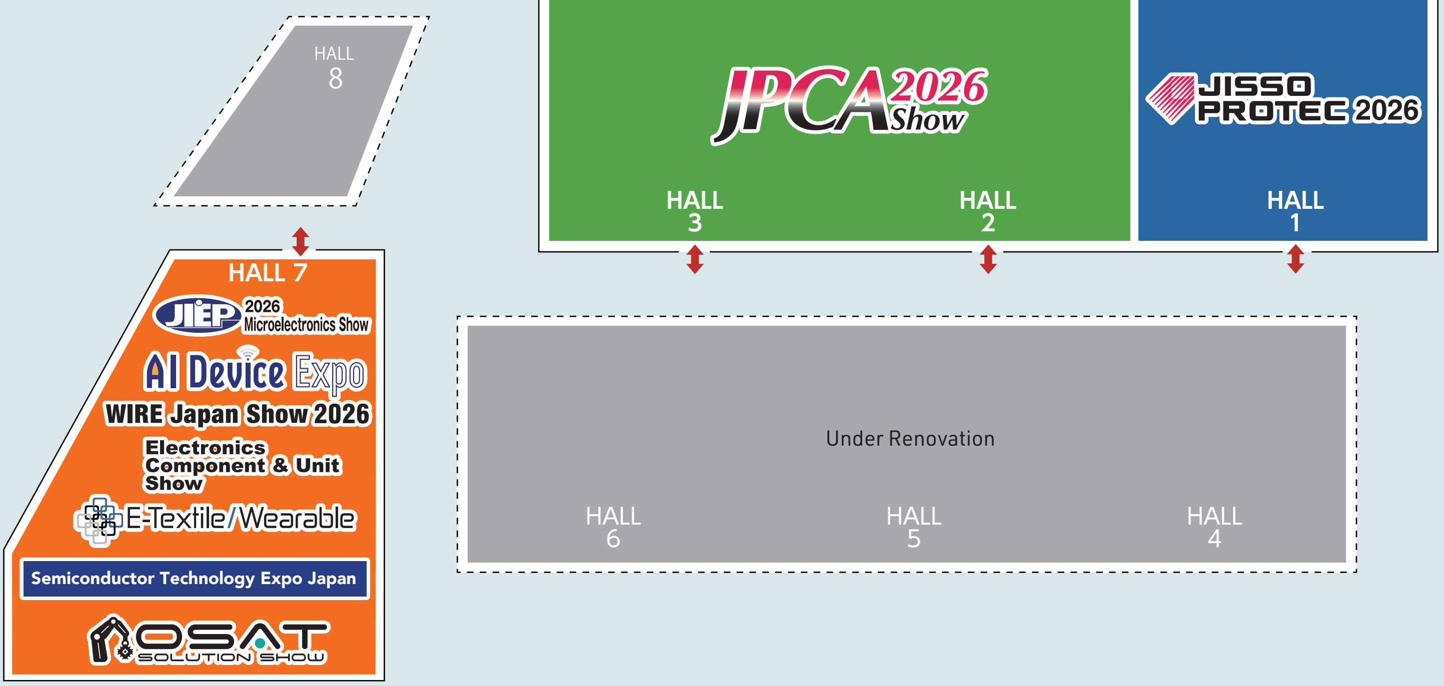
NEW Semiconductor OSAT

OSAT SOLUTION SHOW

Comprehensive technologies / materials / equipment related to semiconductor back-end processes (package materials, assembly equipment, wafer-level packages, fan-out packages (FO-WLP / FO-PLP), 3D / 2.5D assembly, chiplets, PLP, test systems, handling equipment, package design tools, simulators, etc.)
Trading companies / organizations / others related to semiconductor back-end processes

Co-organizers: Japan Electronics Packaging and Circuits Association (JPCA), Japan OSAT Federation

Exhibition Layout Proposal



2025Exhibition Results

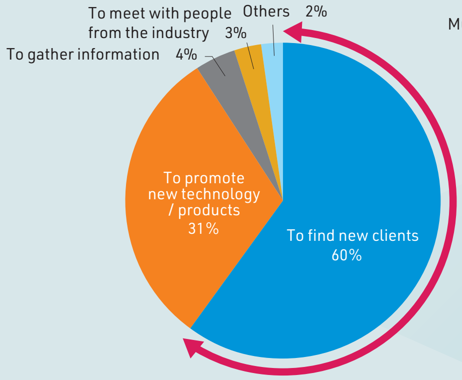
Venue Tokyo Big Sight East Exhibition Halls

Exhibit scale 442 companies / 1,197 booths

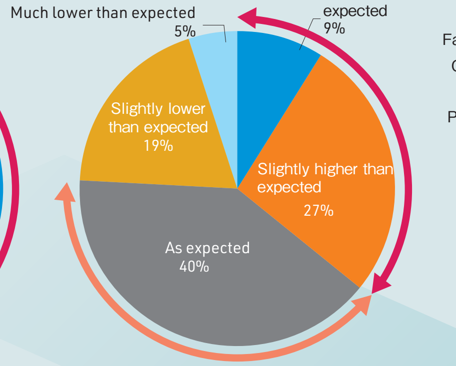
Number of visitors 49,760 people

●Exhibitors Questionnaire

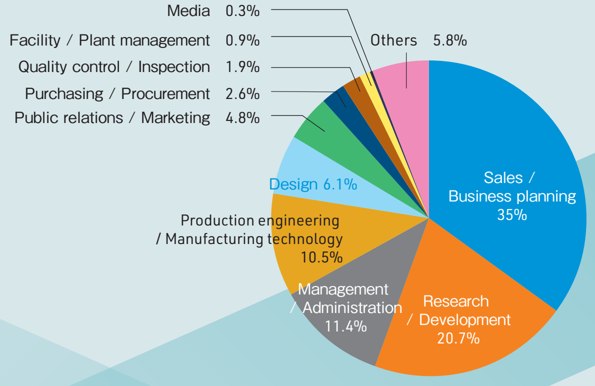
①Reasons for exhibiting



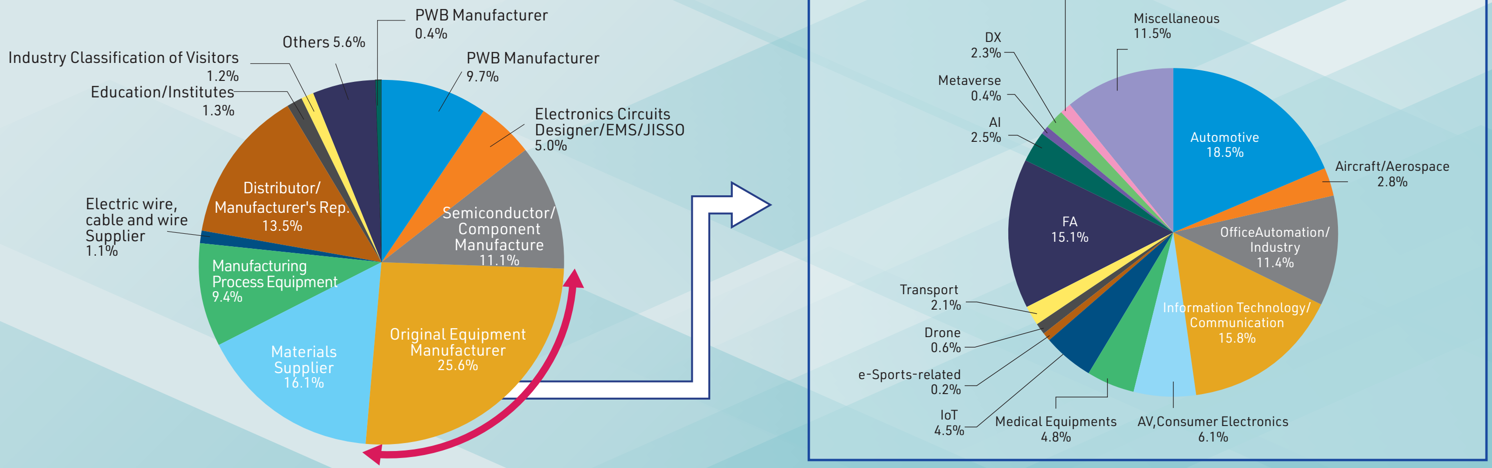
②Effects of exhibiting



● Job classification of visitors



●Industry Classification of Visitors



Numerous key figures from the forefront of manufacturing, including the automotive, information and communications, and factory automation sectors, attended! The event earned high praise as a venue where active technical proposals and business discussions led to the creation of new business opportunities.

Exhibition Fee

Category	1 booth/9m² *Tax included
Non-Members	Yen 498,300
Members *1	Yen 424,600

[*1] Members of the following associations
WECC Member Associations (CPCA, EIPC, ELCINA, HKPCA, IPC, IPCA, KPCA, THPCA, TPCA)
AEIS, KPIA

※ Size of a booth is 9m² (3m × 3m).

※ Fee is for raw space only, Booth construction, cleaning, electricity, water supply, etc. are not included in the exhibition fee.

How to apply (from Friday, November 14, 2025, 10:00 a.m. JST)

Please apply online via the exhibition website (www.jpcashow.com).
Select the exhibition section that best matches your company's products, technologies, and services, and be sure to review the Exhibition Regulations.
For exhibitions with a dedicated application form, the corresponding regulations will apply.
After receiving your application form, an invoice will be issued. Please make payment by the specified deadline (in principle, payment is required before the exhibition).
For those wishing to exhibit at the Semiconductor Technology Expo Japan, please inquire via the Semiconductor Technology Expo Japan website.

Application Deadline

Friday, February 27, 2026

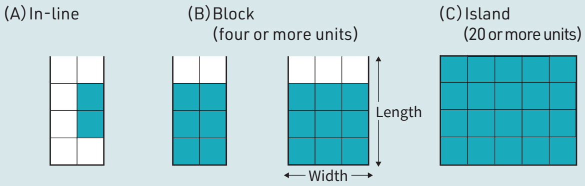
※If all spaces are reserved before the deadline, the application will no longer be accepted.

Cancellation charges

If an exhibit is cancelled to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation	Cancellation charges
Until Friday, February 27, 2026	30% of booth fees
Saturday, February 28 -Tuesday, March 31, 2026	50% of booth fees
Wednesday, April 1 - Thursday, April 30, 2026	70% of booth fees
From Friday,May 1, 2026 onward	100% of booth fees

Booth type



※ In some cases, it may not be possible to prepare the requested booth type.

Assignment of Booth Locations

Booths will be assigned at the Booth Location Selection Meeting (Scheduled to be held in late March 2026).
As a rule, exhibitors will be able to choose their booth locations on a first-come-first-served basis.
※For details, please refer to the Exhibitor Rules and Regulations.

Exhibitor Support Program Option

Promotion services will provide an opportunity to increase your presence at the exhibition.

Package booth Option

●1 booth / basic plan

Price: 121,000 Yen (Tax included)
This plan includes the minimum necessary booth fixtures and fittings, power supply and carpet.
For more details, please refer to the document to be distributed around mid-March 2026.

Schedule prior to the Exhibition (Tentative)

2025 November	2026 February	March	April	May	June
▲ November 14 (Fri.) 10:00 - JST Start of Exhibition Application	▲ February 27 (Fri.) Exhibitor application deadline	▲ Mid-March Exhibitor Manual available ▲ Late March Booth Location Selection Meeting ◀ Mid-March onwards ▶ Submission of necessary forms	▲ Mid-April Sending Invitations Visitor Registration begins		▲ June 8 (Mon.) - 9 (Tue.) Installation period June 10 (Wed.) - June 12 (Fri.) Exhibition open ※Immediate removal on the last day

Managed by
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Official Website